



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



F

E

D

C

B

A

F

E

D

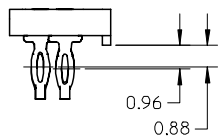
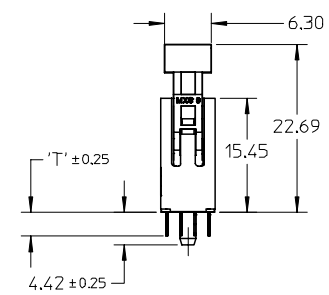
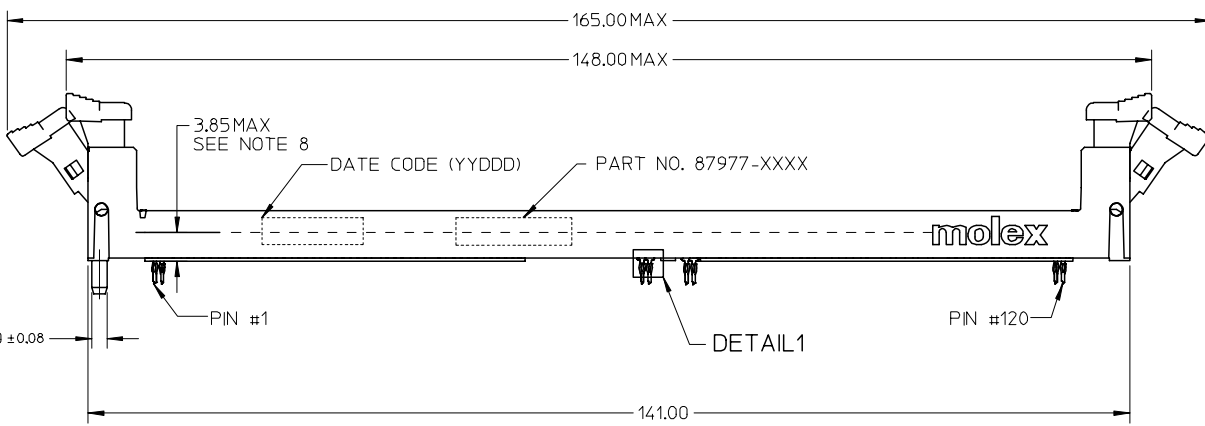
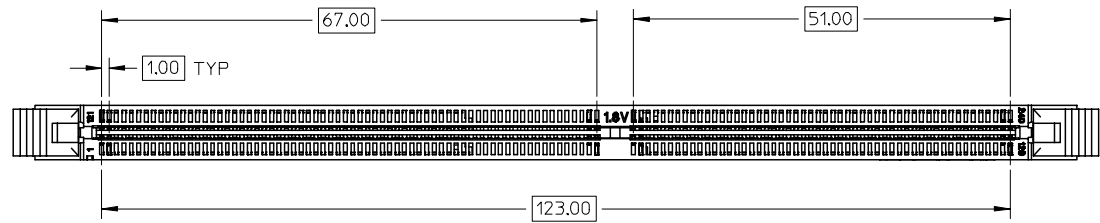
C

B

A

NOTES:

1. MATERIALS  
 HOUSING - HIGH TEMP. NYLON, GLASS FILLED, UL 94V-0, BLACK  
 EJECTOR - HIGH TEMP. NYLON, GLASS FILLED, UL 94V-0, NATURAL  
 BASE PLATE - HIGH TEMP. NYLON, GLASS FILLED, UL 94V-0  
 TERMINAL - COPPER ALLOY
2. PLATING - SEE TABLE IN SHEET 5.
3. CARD SLOT ACCEPTS 1.27±0.10 MM MODULE THICKNESS.  
 (MEASURED OVER P.C. PADS)
4. RECOMMENDED MODULE LAYOUT SHALL BE AS PER JEDEC MO-14-066.
5. REFER TO PRODUCT SPEC. PS-87977-030 FOR PERFORMANCE SPECIFICATIONS.
6. PRODUCT SHALL BE PACKED IN TRAY.
7. PRODUCT SHALL HAVE DATE CODE STAMPED ON SIDE OF HOUSING.
8. PRODUCT IS SUITABLE FOR WAVE SOLDERING ONLY.
9. KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR IS MOUNTED ONTO THE PCB WHICH DOES NOT INCLUDE THE LATCH.
10. REFER TO CRITICAL JEDEC INFORMATION FOR SOCKET OUTLINE PER SO-001.
11. DIMM MODULE SEATING PLANE FROM TOP OF PCB.
12. CONTACT MOLEX FOR AVAILABILITY OF PRODUCT OPTIONS.



DETAIL 1

EC NO: S2006-0241	2005/09/01	2005/09/01	2005/09/02
DRWN: CCTEH	CHKD: SRRAMESH	APPR: GGLEE	
A			

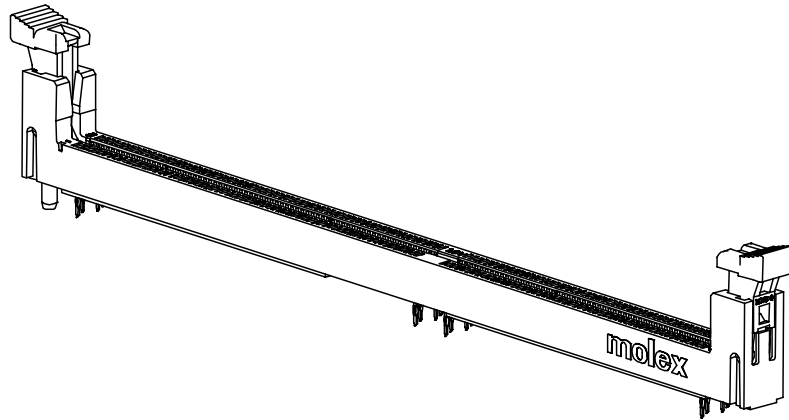
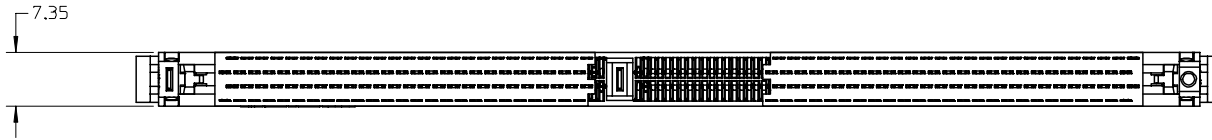
REV	DESCRIPTION
	QUALITY SYMBOLS
	▽=0
	∇=0

GENERAL TOLERANCES (UNLESS SPECIFIED)	
mm	INCH
4 PLACES ± ---	± ---
3 PLACES ± ---	± ---
2 PLACES ± 0.20	± ---
1 PLACE ± ---	± ---
ANGULAR ± 5 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE	
MM ONLY	
DRAWN BY	DATE
CCTEH	2005/01/10
CHECKED BY	DATE
SRRAMESH	2005/08/30
APPROVED BY	DATE
GGLEE	2005/08/30
MATERIAL NO.	DOCUMENT NO.
SEE TABLE	SD-87977-020

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
NTS	METRIC	
SALES DRAWING		
DDR FB DIMM 1.00MM PITCH		
240 CKTS VERT. PRESS-FIT		
MOLEX INCORPORATED		
SHEET NO.		1 OF 5

10 9 8 7 6 5 4 3 2 1



F

E

D

C

B

A

F

E

D

C

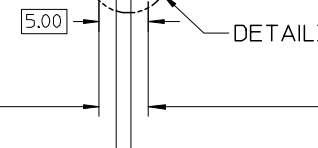
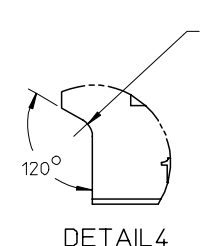
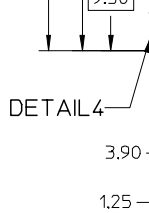
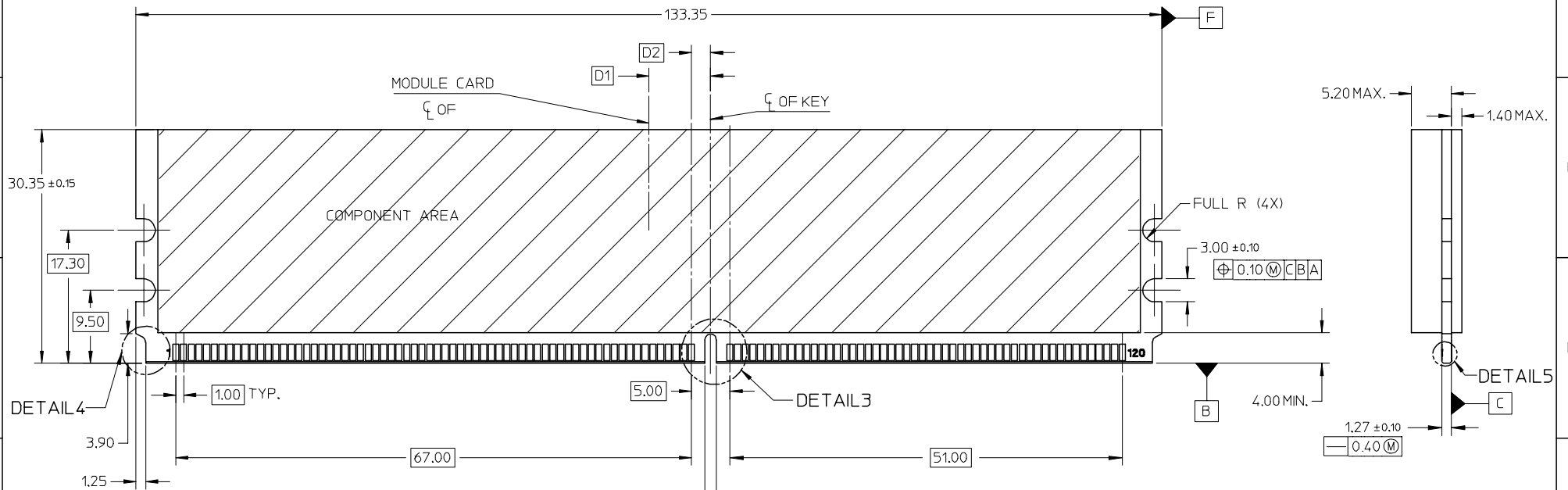
B

A

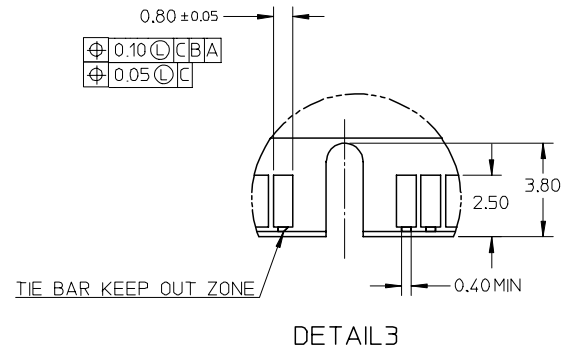
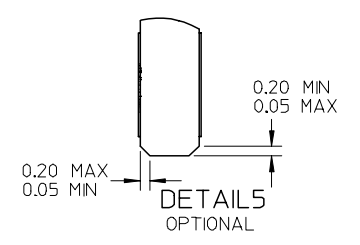
EC NO: S2006-0241 2005/09/01 DRWN: CCTEH 2005/09/01 CHKD: SRRAMESH 2005/09/01 APPR: GGLEE 2005/09/02	DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± ---	mm INCH	DRAWN BY CCTEH	DATE 2005/01/10	TITLE SALES DRAWING DDR FB DIMM 1.00MM PITCH 240 CKTS VERT. PRESS-FIT				
			ANGULAR ± 5 °	APPROVED BY GGLEE	DATE 2005/08/30	MOLEX INCORPORATED					
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-87977-020	SHEET NO. 2 OF 5					

9 8 7 6 5 4 3 2 1

RECOMMENDED MODULE LAYOUT  
(VARIATION AB, AS PER JEDEC MO-256A)



KEY LOCATION	VOLTAGE	DIM 'D2'	DIM 'D1'
CENTER	1.8V	2.50	8.00



EC NO: S2006-0241	2005/09/01	QUALITY SYMBOLS
DRWN: CTEH	2005/09/01	▽=0
CHKD: SRRAMESH	2005/09/01	∇=0
APPR: GGLEE	2005/09/02	
REV	DESCRIPTION	
A		

GENERAL TOLERANCES (UNLESS SPECIFIED)	
mm	INCH
4 PLACES ± ---	± ---
3 PLACES ± ---	± ---
2 PLACES ± 0.20	± ---
1 PLACE ± ---	± ---
ANGULAR ± 5 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE	
MM ONLY	
DRAWN BY	DATE
CTEH	2005/01/10
CHECKED BY	DATE
SRRAMESH	2005/08/30
APPROVED BY	DATE
GGLEE	2005/08/30
MATERIAL NO.	DOCUMENT NO.
SEE TABLE	SD-87977-020

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
NTS	METRIC	
SALES DRAWING		
DDR FB DIMM 1.00MM PITCH		
240 CKTS VERT. PRESS-FIT		
MOLEX INCORPORATED		
SHEET NO.	3 OF 5	

10 9 8 7 6 5 4 3 2 1

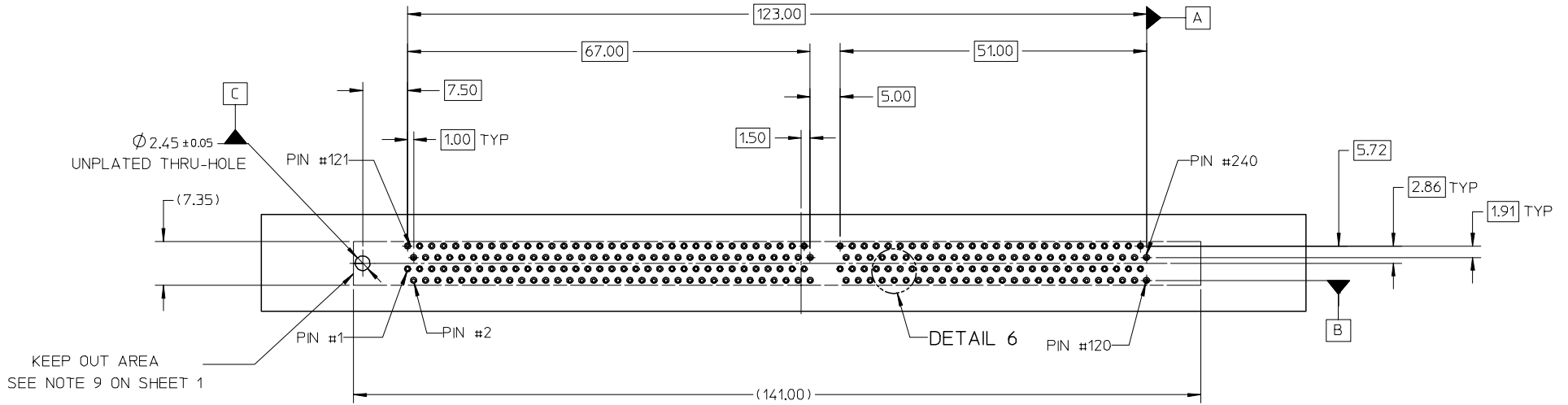
F

F

RECOMMENDED PCB HOLE PATTERN  
SEE TABLE IN SHEET 5 FOR  
RECOMMENDED PCB THICKNESS

E

E

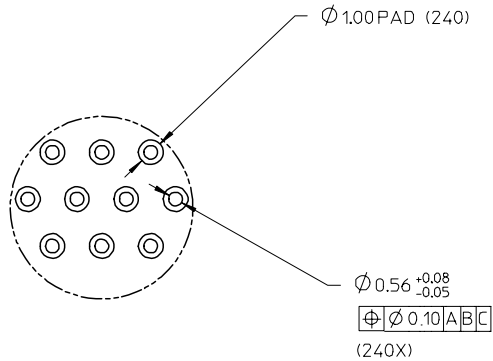


D

D

C

C



DETAIL 6

B

B

A

A

EC NO: S2006-0241 DRWN: CTEH 2005/09/01 CHKD: SRRAMESH 2005/09/01 APPR: GGLEE 2005/09/02	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION															
	$\nabla = 0$ $\nabla C = 0$	<table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.20</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± ---</td> <td>± ---</td> </tr> </tbody> </table> ANGULAR ± 5 °		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.20	± ---	1 PLACE	± ---	± ---	MM ONLY DRAWN BY: CTEH DATE: 2005/01/10 CHECKED BY: SRRAMESH DATE: 2005/08/30 APPROVED BY: GGLEE DATE: 2005/08/30	NTS METRIC	MILEX MOLEX INCORPORATED	TITLE: SALES DRAWING DDR FB DIMM 1.00MM PITCH 240 CKTS VERT. PRESS-FIT
		mm	INCH																		
	4 PLACES	± ---	± ---																		
3 PLACES	± ---	± ---																			
2 PLACES	± 0.20	± ---																			
1 PLACE	± ---	± ---																			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	MATERIAL NO. DOCUMENT NO. SD-87977-020	SHEET NO. 4 OF 5																		
SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																				

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

PART NO.	KEY POS.	DIM 'T'	RECOMEMDED PCB THICKNESS	PLATING OPTION	LATCH COLOR
87977-0021	CENTER (1.8V)	3.15	3.30	0.38uM / 15 uIN MIN. GOLD ON CONTACT, 1.52uM/ 60uIN MIN. PURE TIN ON SOLDERTAILS, 1.27uM/ 50uIN MIN. NICKEL UNDERPLATE	NATURAL
87977-0051				0.76uM / 30 uIN MIN. GOLD ON CONTACT, 1.52uM/ 60uIN MIN. PURE TIN ON SOLDERTAILS, 1.27uM/ 50uIN MIN. NICKEL UNDERPLATE	
87977-9001				0.38uM / 15 uIN MIN. GOLD ON CONTACT, 1.52uM/ 60uIN MIN. TIN ON SOLDERTAILS, 1.27uM/ 50uIN MIN. NICKEL UNDERPLATE	BLACK

F  
E  
D  
C  
B  
A

F  
E  
D  
C  
B  
A

EC NO: S2006-0241 2005/09/01 DRWN: CTEH 2005/09/01 CHKD: SRRAMESH 2005/09/02 APPR: GGLEE	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
		$\nabla = 0$ $\nabla \square = 0$	mm      INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± --- ANGULAR ± 5 °	MM ONLY	NTS	METRIC	DRAWN BY      DATE CTEH      2005/01/10 CHECKED BY      DATE SRRAMESH      2005/08/30 APPROVED BY      DATE GGLEE      2005/08/30	TITLE SALES DRAWING DDR FB DIMM 1.00MM PITCH 240 CKTS VERT. PRESS-FIT
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	MATERIAL NO. MOLEX INCORPORATED	DOCUMENT NO. SD-87977-020	SHEET NO. 5 OF 5	
		A			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

9 8 7 6 5 4 3 2 1